

General Description

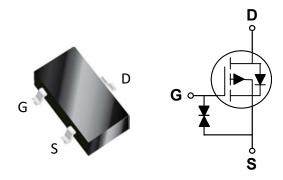
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
-60 V	4 Ω	-0.5 A

Features

- R_{DS(ON)}≦4Ω@V_{GS}= -10V
- · Improved dv/dt capability
- · Fast switching
- · Green Device Available
- · G-S ESD Protection Diode Embedded

SOT-23S Pin Configuration



Applications

- Notebook
- · Load Switch
- · Battery Protection
- · Hand-held Instruments

Absolute Maxin	osolute Maximum Ratings T _C =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units				
V_{DS}	Drain-Source Voltage	-60	V				
V_{GS}	Gate-Source Voltage	±20	V				
L	Drain Current - Continuous (T _A =25°C)	-0.5	Α				
I _D	Drain Current - Continuous (T _A =70°C)	-0.4	Α				
I _{DM}	Drain Current - Pulsed (NOTE 1)	-2	Α				
P_{D}	Power Dissipation (T _A =25°C)	1.56	W				
ı D	Power Dissipation – Derate above 25°C	12.5	mW/°C				
T_J	Operating Junction Temperature Range	-55 to 150	°C				
T_{STG}	Storage Temperature Range	-55 to 150	°C				

Thermal Characteristics					
Symbol	Symbol Parameter				
$R_{\theta JA}$	Thermal Resistance Junction to Ambient		80	°C/W	





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V , I_D = -250uA	-60	1		V
I _{DSS}	IDrain-Source Leakage Current	V_{DS} = -60V , V_{GS} = 0V , T_{J} =25°C		1	-1	uA
		V_{DS} = -48V , V_{GS} = 0V , T_{J} =125°C			-10	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±20	uA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = -10V$, $I_D = -0.3A$		2.5	4	
		V_{GS} = -4.5V , I_{D} = -0.2A		3.3	5.5	22
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = -250uA$	-1.2		-2.5	V
gfs	Forward Transconductance	$V_{DS} = -10V$, $I_{D} = -0.3A$		0.4		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	V 20V V 40V L 0.5A		2.8	4.2	
Q_{gs}	Gate-Source Charge	V_{DS} = -30V , V_{GS} = -10V , I_{D} = -0.5A (NOTE 2 \ 3)		0.96	1.5	nC
Q_{gd}	Gate-Drain Charge	(10012 2 1 3)		0.6	0.9	
$T_{d(on)}$	Turn-On Delay Time	V_{DD} = -30V , V_{GS} = -10V , R_{G} =6 Ω , I_{D} = -0.5A (NOTE 2 \cdot 3)		3	6	
T _r	Rise Time			5	10	nS
$T_{d(off)}$	Turn-Off Delay Time			14	27	113
T _f	Fall Time			9	17	
C _{iss}	Input Capacitance	V _{DS} = -30V , V _{GS} = 0V , F= 1MHz		30.5	45	
C _{oss}	Output Capacitance			15.1	22.5	pF
C_{rss}	Reverse Transfer Capacitance			7	10.5	

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current	V _G = V _D = 0V,Force Current			-0.5	Α
I _{SM}	Pulsed Source Current				-1	Α
V_{SD}	Diode Forward Voltage	V_{GS} = 0V , I_{S} = -0.2A , T_{J} = 25°C			-1	V
t _{rr}	Reverse Recovery Time	$V_R = -50V$, $I_S = -0.5A$,		13.5		nS
Q_{rr}	Reverse Recovery Charge	dl/dt=100A/us , T _J =25°C		3		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





Characteristics Curves

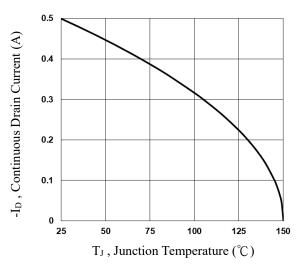


Fig.1 Continuous Drain Current vs. Tc

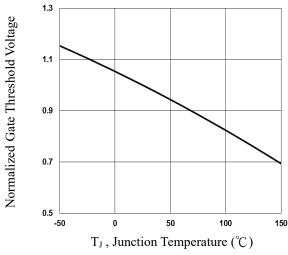


Fig.3 Normalized V_{th} vs. T_J

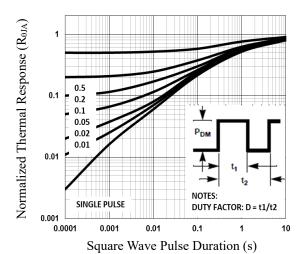


Fig.5 Normalized Transient Impedance

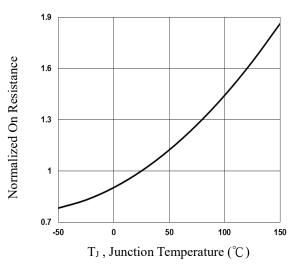


Fig.2 Normalized RDSON vs. TJ

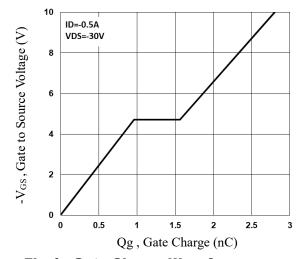


Fig.4 Gate Charge Waveform

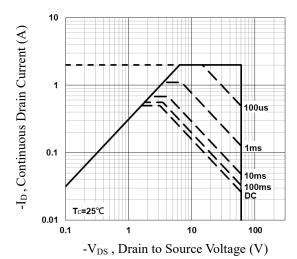


Fig.6 Maximum Safe Operation Area





Characteristics Curves

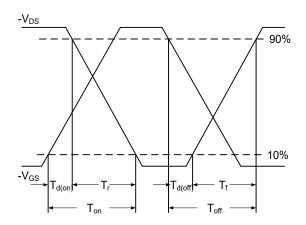


Fig.7 Switching Time Waveform

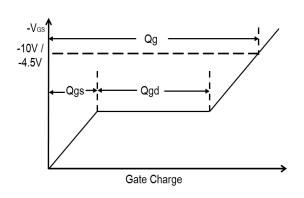
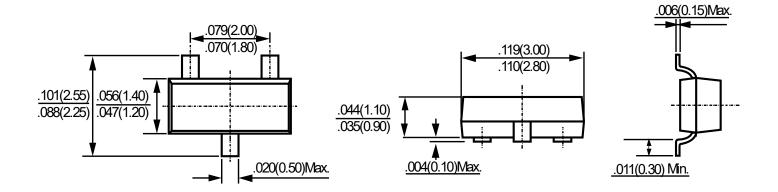


Fig.8 Gate Charge Waveform

Package Outline Dimensions



SOT-23S

Dimensions in inches and (millimeters)





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